

09/821,546

2811  
SFW

January 3, 2007

To: Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Fr: Stephen B. Ackerman, Reg. No. 37,761  
28 Davis Avenue  
Poughkeepsie, N.Y. 12603

Subject:

Serial No. 09/821,546 03/30/2001

J. Y. LEE

"A STRUCTURE AND MANUFACTURING  
METHOD OF CHIP SCALE PACKAGE"

Grp. Art Unit: 2811

D. W. OWENS

#### RESPONSE NON-FINAL OFFICE ACTION

Dear Sir:

In response to the Non-Final Office Action dated October 6, 2006, please amend the above-identified application for patent and consider the remarks as follows:

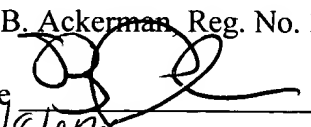
#### CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on Jan. 8, 2007.

Stephen B. Ackerman, Reg. No. 37,761

Signature

Date

  
1/8/07

Amendments to the Claims are reflected in the listing of the Claims which begins on page 3 of this paper.

Remarks/Arguments begin on page 24 of this paper.